The medical electronics sector features a broad range of appliances for inpatient, outpatient and even home care. The growing requirements for high sensitivity, accuracy and long-term stability of temperature and pressure sensors for use in medical devices were taken into account during development. The company’s products have long been standard issue in the context of hospital treatment.

- Low resistance tolerance and individual calibration options ensure that TDK’s temperature sensors meet all requirements for reliable and accurate measurement.
- Its miniaturized pressure sensor transmitters for anesthesia and respiratory equipment are particularly robust and resistant to aggressive media.
- The pressure sensor elements combine a low-pressure range with high sensitivity and long-term stability.
TDK’s temperature and pressure sensors can also be used to monitor device functionality – e.g. in the context of battery management. Especially when small mobile medical appliances are charging up, it is important to constantly monitor the operating temperature of (rechargeable) batteries. (The electrochemical reactions used during monitoring are mostly temperature-dependent, which is why the temperature factor is so vital to fast, accurate analysis.) Additionally, both our pressure sensor elements and pressure transmitters are qualified for a very broad temperature range that by far exceeds industry standards.

Examples of key medical device applications for TDK temperature and pressure sensors:

- Anesthesia and respiration apparatus
- Body temperature control
- Respiratory care and sleep apnea
- Infusion pumps
- Blood pressure monitoring
- Cleaning equipment
- General patient monitoring
- Battery and power management for medical devices

### Pressure sensors dies and transmitters

#### Pressure sensor dies C33/ C39

<table>
<thead>
<tr>
<th>Description</th>
<th>Technical data</th>
</tr>
</thead>
</table>
| - Miniaturized design  
- Absolute, gauge pressure measurements  
- Media-protected pressure dies for harsh environments | - Typical output: 120 mV  
- Pressure range: 0 … 1.2 bar to 0 … 10 bar, absolute  
- Dimensions: 1.0 x 1.0 x 0.4 mm³ |
| C33 |  
- Pressure range: 0 … 1.2 bar, absolute  
- Dimensions: 0.65 x 0.65 x 0.24 mm³ |

#### Pressure sensor die C35

<table>
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<tr>
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</table>
| - Outstanding long-term stability  
- Low pressure measurements at small footprint  
- Various wire bond options (surrounded wire bonding and direct die to die wire bonding) | - 0 … 0.1 bar, gauge  
- Operating temperature: –40 °C up to +150 °C  
- Non-linearity typ. 0.20% FS  
- Defined signal stability of ±0.2% FS  
- Narrow tolerance of sensitivity ±100 mV  
- Size 2.05 x 2.05 mm² |
# Pressure Sensors for Medical Appliances

## Pressure sensors dies and transmitters

### Pressure sensor dies C32/ C38

<table>
<thead>
<tr>
<th>Description</th>
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</table>
| - All around bond pad layout (C32)  
- Layout for direct die to die wire bonding (C38)  
- Flat piezo structures  
- Thin passivation layer system  
- No need for metal layer passivation  
- Optimized piezo-structure for high signal stability  
- Media-protected pressure dies for harsh environments | - Operating temperatures: –40 °C to +135 °C  
- Temperature hysteresis of offset typ. 0.1% FS  
- Size 1.65 x 1.65 mm²  
- Pressure range: C32 0.4 … 40 bar, absolute, gauge  
- Pressure range: C38 10 … 40 bar, absolute, gauge |

### Pressure transmitter, low-profile pressure transmitter with digital interface

<table>
<thead>
<tr>
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</table>
| - High mechanical robustness  
- High accuracy at low pressures  
- Excellent “absolute pressure” accuracy  
- No tubes required  
- Easy screw-on mounting  
- With digital or analogue interface | - Accuracy: ±1% FS  
- Max. rated pressures: 16 mbar to 7 bar  
- Operating temperature: –25 °C ≤ TOP ≤ +85 °C  
- Miniaturized and low profile (24 x 26 x 6 mm³) |

### Pressure transmitter, MiniCell

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</table>
| - Pressure element and signal conditioner mounted in a ceramic housing filled with oil  
- High media resistance due to high-alloy steel  
- Absolute, relative or differential pressure measurements  
- Various flange geometries possible | - Radiometric analog output signal: 0.5 … 4.5 V  
- Operating temperature: –40 °C ≤ TOP ≤ +140 °C  
- High accuracy (< 1.5% FS) over full temperature range and lifetime  
- Small dimensions < 3 cm³ |
## NTC Thermistors for Medical Appliances

### NTC thermistor temperature sensors

<table>
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<th>Description</th>
<th>Technical data</th>
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</table>
| **G15*1 glass-encapsulated NTC thermistors with insulation** | **Temperature range:**
| ● Thermistor for precise and fast temperature measurement | –55 °C up to +260 °C
| ● Excellent long-term stability | **High insulation strength:**
| ● Temperature measurement with media contact | Test voltage 500 V DC (1 s)
| ● Simplified handling due to insulation of glass body and leads | **Very small dimensions,**
| ● Dumet wires (copper-clad FeNi) | head diameter: 1.4 mm
| ● Easy and flexible mounting: crimping, soldering or welding | **Packaging in bulk or stripe** |
| ● Packaging in bulk or stripe | **Technical data** |

### L862 epoxy-encapsulated NTC thermistors

<table>
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</table>
| **Lead-free** | **Temperature range:**
| **Tight temperature tolerances** | –55 °C up to +155 °C
| **High long-term stability** | **High accuracy over a wide temperature range** |
| **High thermal shock resistance** | **Insulated silver plated nickel wire** |
| **Easy and flexible mounting: crimping, soldering or welding** | **Packaging in bulk or stripe** |
| **Packaging in bulk or stripe** | **Technical data** |

### L860 bondable NTC thermistor chips

<table>
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| **Lead-free** | **Temperature range:**
| **Low total surface demand on DCB (0.15 mm²)** | –40 °C up to +150 °C
| **Planar chip mounting** (bonding, sintering, soldering, gluing) | **Top and bottom surface metallized** (metallization depending on type in gold or silver)
| **High accuracy and sensitivity** | **Very small dimensions** (smallest: 0.39 x 0.39 x 0.20 mm³)
| **UL recognised and tested according to AEC-Q200** | **Packaging: on tape (within 8-inch frame)** |
| **Packaging: on tape (within 8-inch frame)** | **Technical data** |

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**Important information:** Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products. We expressly point out that these statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. It is incumbent on the customer to check and decide whether a product is suitable for use in a particular application. This publication is only a brief product survey which may be changed from time to time. Our products are described in detail in our data sheets. The important notes (www.tdk-electronics.tdk.com/ImportantNotes) and the product-specific Cautions and warnings must be observed. All relevant information is available through our sales offices.

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